Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier in a SOT429N (TO-247) plastic package intended for use in applications requiring very high inrush current capability, high thermal cycling performance and high junction temperature capability ($T_{j(max)} = 150 \, ^{\circ}\text{C}$).

2. Features and benefits

- High junction operating temperature capability (T_{i(max)} = 150 °C)
- Very high current surge capability
- Planar passivated for voltage ruggedness and reliability
- High thermal cycling performance
- High voltage capability

3. Applications

- Line rectifying 50/60 Hz
- Soft start AC motor control
- · DC motor control
- Power converter
- · AC power control
- Lighting and temperature control
- Uninterruptible Power Supply (UPS)
- Solid State Relay (SSR)
- Traction battery charging

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit			
Absolute r	Absolute maximum rating						
V_{DRM}	repetitive peak off-state voltage		1600	V			
I _{T(RMS)}	RMS on-state current	half sine wave; T _{mb} ≤ 117°C; Fig. 1; Fig. 2; Fig. 3	126	А			
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 10 \text{ ms}$; Fig. 4; Fig. 5	850	А			
		half sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 8.3 \text{ ms}$	930	А			
T _j	junction temperature		150	°C			

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Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static cha	Static characteristics						
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 7; Fig. 8		-	-	80	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 10</u>		-	-	200	mA
V _T	on-state voltage	I _T = 80 A; T _j = 25 °C; <u>Fig. 11</u>		-	-	1.47	V
Dynamic	Dynamic characteristics						
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 1070 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		1000	-	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		A K
2	А	anode		G sym037
3	G	gate		Symoor
mb	A	mounting base; connected to anode	TO-247 (SOT429N)	

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
TYN80W-1600T	TO-247	Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247	SOT429N

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		1600	V
V_{RRM}	repetitive peak reverse voltage		1600	V
I _{T(AV)}	average on-state current	half sine wave; T _{mb} ≤ 117°C;	80	Α
$I_{T(RMS)}$	RMS on-state current	half sine wave; T _{mb} ≤ 117°C; <u>Fig. 1; Fig. 2; Fig. 3</u>	126	А
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	850	А
		half sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 8.3 \text{ ms}$	930	А
l ² t	I ² t for fusing	t _p = 10 ms; sine wave	3610	A ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 200 mA	150	A/µs
I _{GM}	peak gate current		8	Α
V_{RGM}	peak reverse gate voltage		5	V
P _{GM}	peak gate power		20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	1	W
T _{stg}	storage temperature		-40 to 150	°C
T _j	junction temperature		150	°C

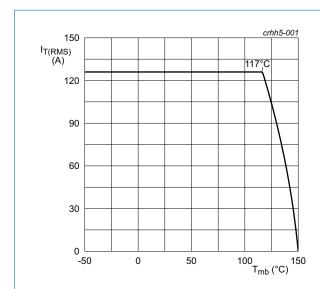


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

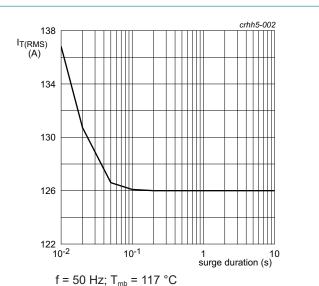
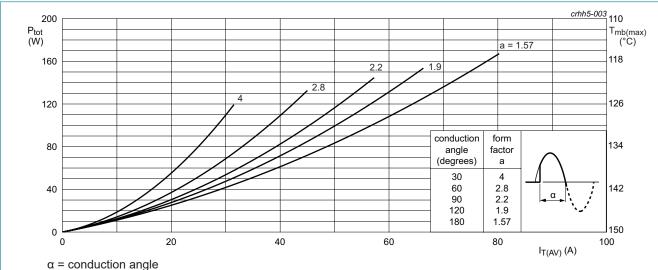


Fig. 2. RMS on-state current as a function of surge duration; maximum values

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a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

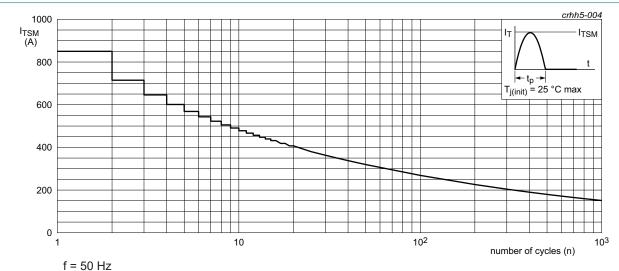
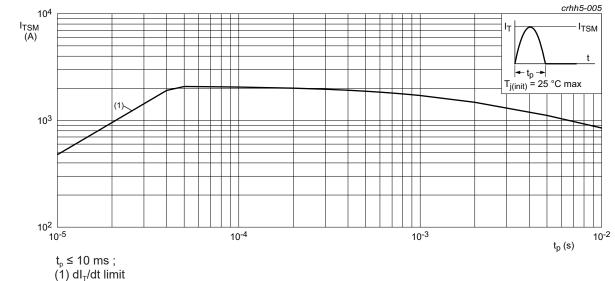


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	Fig. 6	-	-	0.2	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W

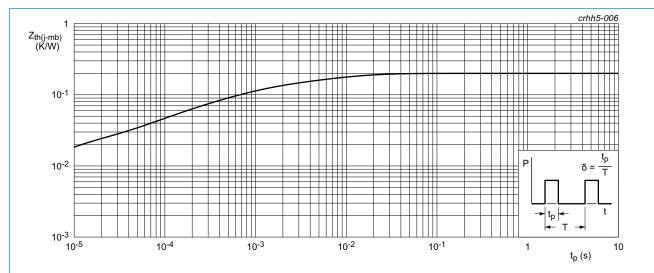


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Mi	n Typ	Max	Unit
Static cha	racteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 7; Fig. 8	-	-	80	mA
I _L	latching current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 9$	-	-	300	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 10</u>	-	-	200	mA
V _T	on-state voltage	I _T = 80 A; T _j = 25 °C; <u>Fig. 11</u>	-	-	1.47	V
V _{GT}	gate trigger voltage	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 12	-	0.7	1	V
		$V_D = 800 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 °C;$ Fig. 12	0.2	25 0.4	-	V
I_D	off-state current	V _D = 1600 V; T _j = 125 °C	-	-	3	mA
I _R	reverse current	V _D = 1600 V; T _j = 125 °C	-	-	3	mA
Dynamic (characteristics					'
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 1070 V; T_{j} = 125 °C; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform; gate open circuit	15	00 -	-	V/µs
		V_{DM} = 1070 V; T_{j} = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	10	00 -	-	V/µs
t _{gt}	gate-controlled turn-on time	$I_{TM} = 40 \text{ A}; V_D = 800 \text{ V}; I_G = 100 \text{ mA};$ $(dI_G/dt)_M = 0.5 \text{ A/µs}; T_j = 25 \text{ °C}$		2	-	μs
t _q	commutated turn-off time	$V_{DM} = 1070 \text{ V}; T_j = 125 ^{\circ}\text{C}; I_{TM} = 80 \text{ A};$ $V_R = 25 \text{ V}; dV_D/dt = 50 \text{ V}/\mu\text{s}; (dI_T/dt)_M = 30 \text{ A}/\mu\text{s}; (V_{DM} = 67\% \text{ of } V_{DRM})$		150	-	μs

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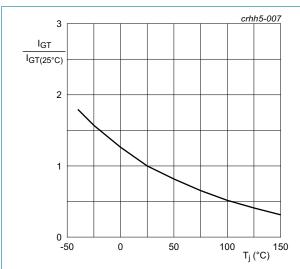


Fig. 7. Normalized gate trigger current as a function of junction temperature

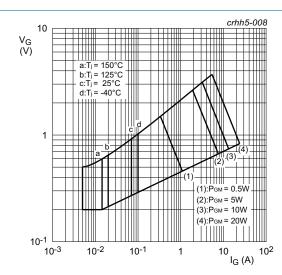


Fig. 8. Gate voltage as a function of gate current

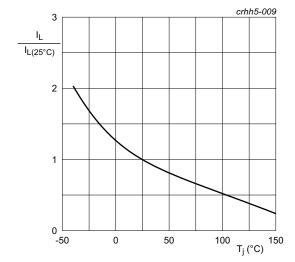


Fig. 9. Normalized latching current as a function of junction temperature

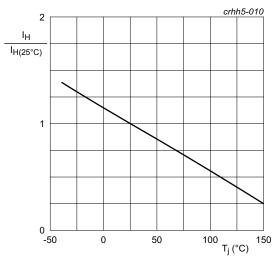
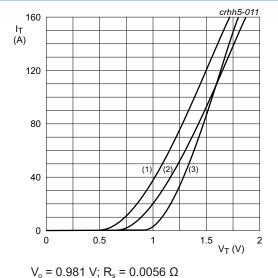


Fig. 10. Normalized holding current as a function of junction temperature



(1) $T_j = 150$ °C; typical values (2) $T_j = 150$ °C; maximum values (3) $T_i = 25$ °C; maximum values VGT(25°C)

1.5

1

0.5

0

-50

0

50

100

T_j (°C)

150

Fig. 12. Normalized gate trigger voltage as a function of junction temperature

Fig. 11. On-state current as a function of on-state voltage

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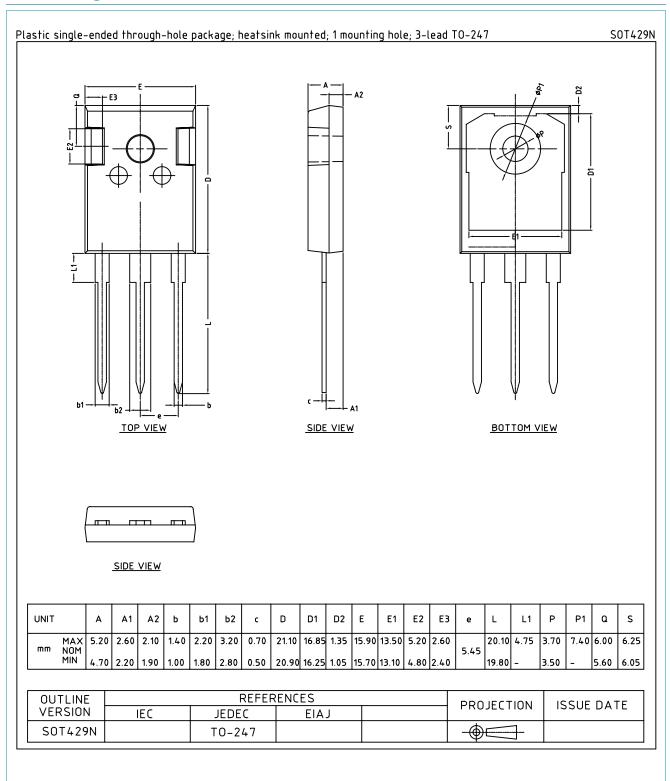
VGT

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10. Package outline



11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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